

Title (en)

ADHESIVE TAPE STAMP AND METHOD FOR STAMPING AN ADHESIVE TAPE SECTION ONTO AN OBJECT

Title (de)

KLEBEBANDSTEMPLER UND VERFAHREN ZUM AUFSTEMPELN EINES KLEBEBANDABSCHNITTS AUF EIN OBJEKT

Title (fr)

DISPOSITIF POUR APPOSER UN RUBAN ADHÉSIF ET PROCÉDÉ POUR APPOSER UNE SECTION DE RUBAN ADHÉSIF SUR UN OBJET

Publication

EP 2134636 B1 20150617 (DE)

Application

EP 08716589 A 20080318

Priority

- EP 2008002127 W 20080318
- DE 102007014055 A 20070321

Abstract (en)

[origin: WO2008113548A1] The invention is based on the aim of providing a novel office tool, and a corresponding method, wherein various application advantages of known office tools are combined. The invention provides an adhesive tape stamp 1 that is configured to implement a course of movement, wherein an adhesive tape section having a defined length is pressed onto an object in a stamping device, having a separating device 12, which is configured and/or disposed in order to separate an adhesive tape end as the adhesive tape section 23 from a continuous adhesive tape 19 at a separation point 22, and having a stamping device 11, wherein the stamping device 11 is configured and/or disposed to press the adhesive tape end and/or the adhesive tape section 23 onto the object in the stamping direction 4.

IPC 8 full level

B65H 35/00 (2006.01)

CPC (source: EP US)

B65H 35/0033 (2013.01 - EP US); **B65H 35/006** (2013.01 - EP US); **Y10T 156/1054** (2015.01 - EP US); **Y10T 156/1348** (2015.01 - EP US); **Y10T 156/1378** (2015.01 - EP US); **Y10T 156/1795** (2015.01 - EP US); **Y10T 225/238** (2015.04 - EP US); **Y10T 225/282** (2015.04 - EP US); **Y10T 225/29** (2015.04 - EP US)

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)

WO 2008113548 A1 20080925; **WO 2008113548 A9 20081120**; CN 101657371 A 20100224; CN 101657371 B 20121003; DE 202007018446 U1 20090226; EP 2134636 A1 20091223; EP 2134636 B1 20150617; JP 2010521574 A 20100624; JP 5560183 B2 20140723; US 2010108250 A1 20100506; US 8794291 B2 20140805

DOCDB simple family (application)

EP 2008002127 W 20080318; CN 200880009210 A 20080318; DE 202007018446 U 20070321; EP 08716589 A 20080318; JP 2010500109 A 20080318; US 53198908 A 20080318